V _{DSS}	40V
R _{DS(on)} (Max.)	7.5mΩ
I _D	±40A
P _D	26W

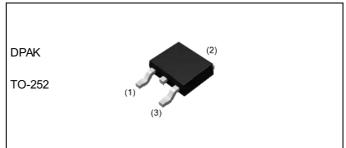
Features

- 1) Low on resistance
- 2) High power package (TO-252)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen free

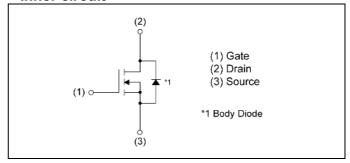
Application

Switching

Outline



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	16
	Basic ordering unit (pcs)	2500
	Taping code	TL
	Marking	RD3G400GN

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	40	V
Continuous drain current	I _D *1	±40	Α
Pulsed drain current	I _{DP} *2	±80	Α
Gate - Source voltage	V _{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *3	20	Α
Avalanche energy, single pulse	E _{AS} *3	3.1	mJ
Power dissipation	P _D *1	26	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Lleit
Parameter		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	ı	4.8	°C/W

● Electrical characteristics (T_a = 25°C)

Davamatav	Cymahal	Conditions	Values			l lait
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	26.2	-	mV/°C
Zero gate voltage drain current	I _{DSS}	I_{DSS} $V_{DS} = 40V, V_{GS} = 0V$		-	1	μА
Gate - Source leakage current	I _{GSS}	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	±500	nA
Gate threshold voltage	V _{GS(th)}	$V_{GS(th)}$ $V_{DS} = V_{GS}$, $I_D = 1mA$		-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$			-4.9	-	mV/°C
Static drain - source	D *4	V _{GS} = 10V, I _D = 40A	-	5.6	7.5	mO.
on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 40A	-	7.0	9.5	mΩ
Gate resistance	R_G	f = 1MHz, open drain	-	2.0	-	Ω
Forward Transfer Admittance	Y _{fs} *4	$V_{DS} = 5V, I_{D} = 20A$	20	-	-	S

^{*1} Tc=25°C, Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s , Duty cycle \leq 1%

^{*3} L \simeq 0.01mH, V_{DD} = 20V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			Lloit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	1410	-		
Output capacitance	C _{oss}	V _{DS} = 20V	-	230	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	62	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 20V, V_{GS} = 10V$	-	8.2	-		
Rise time	t _r *4	I _D = 20A	-	5.6	-		
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 1.0\Omega$	-	41	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	6.8	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Curanh a l	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
T	O *4	Q_g^{*4} $V_{DD} \simeq 20V$	V _{GS} = 10V	-	19	-	
Total gate charge	Q_{g} .			-	9.7	-	5 C
Gate - Source charge	Q _{gs} *4		V _{GS} = 4.5V	-	3.7	-	nC
Gate - Drain charge	Q _{gd} *4				-	2.8	-

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Cymah al	Canditions	Values			1.1-24
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Continuous forward current	I _S	T _a = 25°C	-	-	21	Α
Pulse forward current	I _{SP} *2	1 _a - 25 C	-	-	80	Α
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 21A	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 40A, V _{GS} =0V	-	21	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/µs	-	8.8	-	nC

Fig.1 Power Dissipation Derating Curve

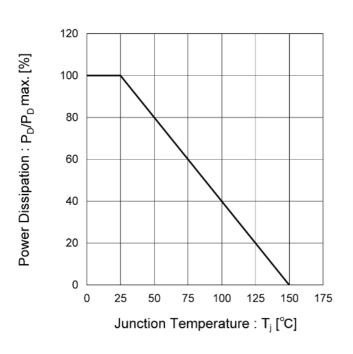


Fig.2 Maximum Safe Operating Area

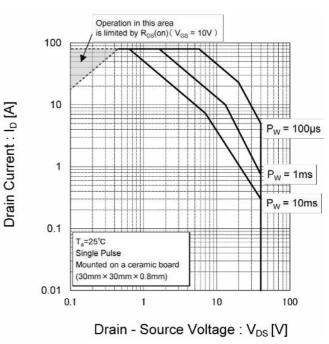


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

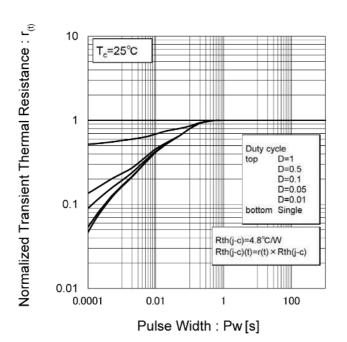


Fig.4 Single Pulse Maximum Power dissipation

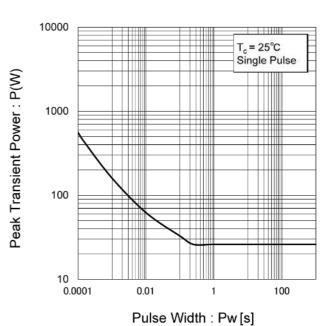


Fig.5 Typical Output Characteristics(I)

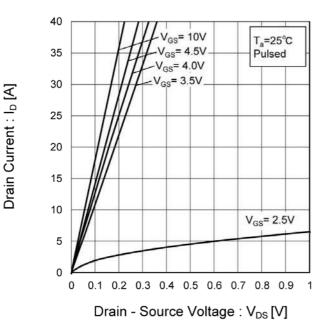
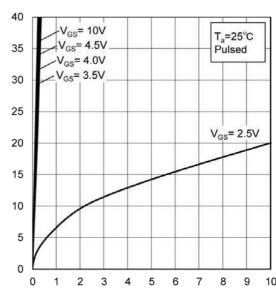


Fig.6 Typical Output Characteristics(II)



Drain Current: I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

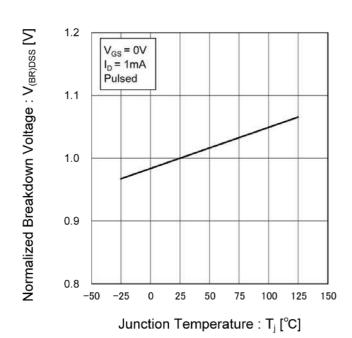


Fig.8 Typical Transfer Characteristics

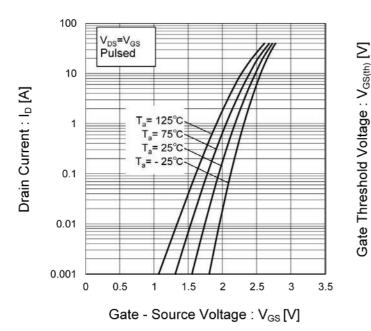


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

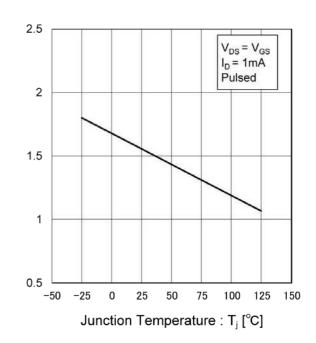


Fig.10 Forward Transfer Admittance vs.
Drain Current

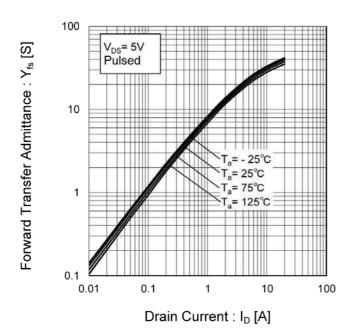
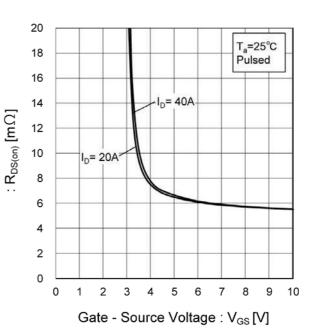


Fig.11 Drain Current Derating Curve

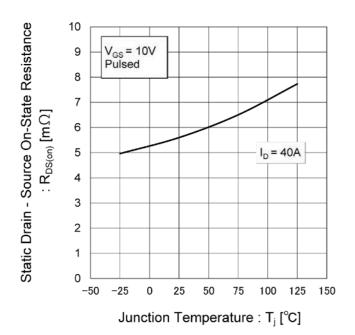
120 100 **Drain Current Dissipation** 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



7/11

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

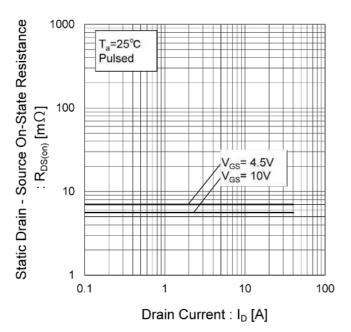


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

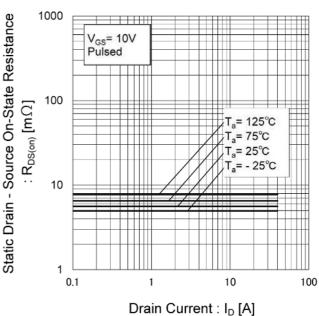


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

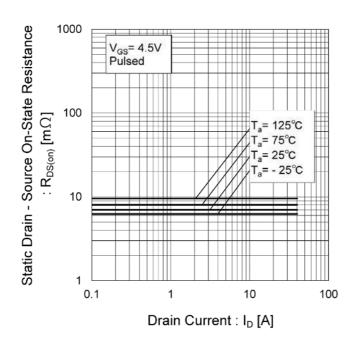


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

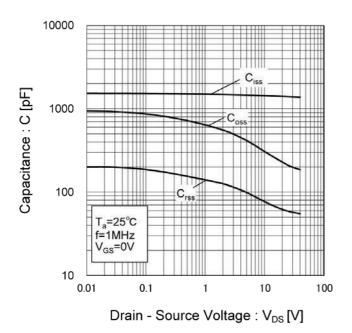


Fig.18 Switching Characteristics

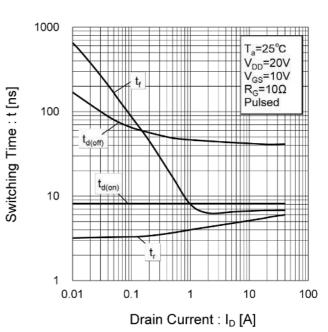


Fig.19 Dynamic Input Characteristics

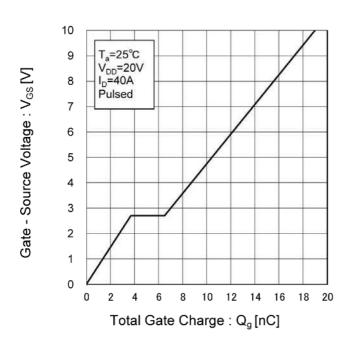
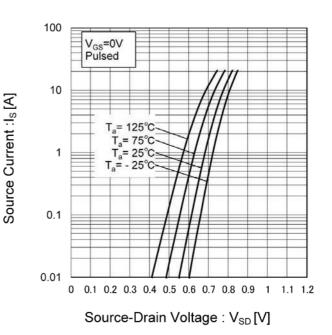


Fig.20 Source Current vs.

Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

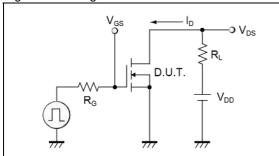


Fig.2-1 Gate Charge Measurement Circuit

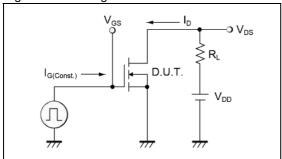


Fig.3-1 Avalanche Measurement Circuit

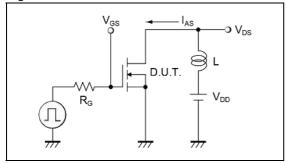


Fig.1-2 Switching Waveforms

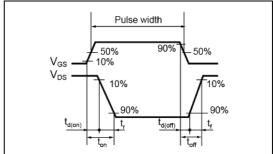


Fig.2-2 Gate Charge Waveform

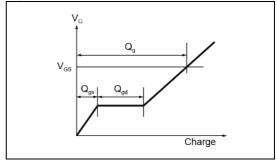
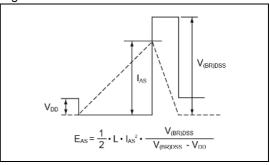
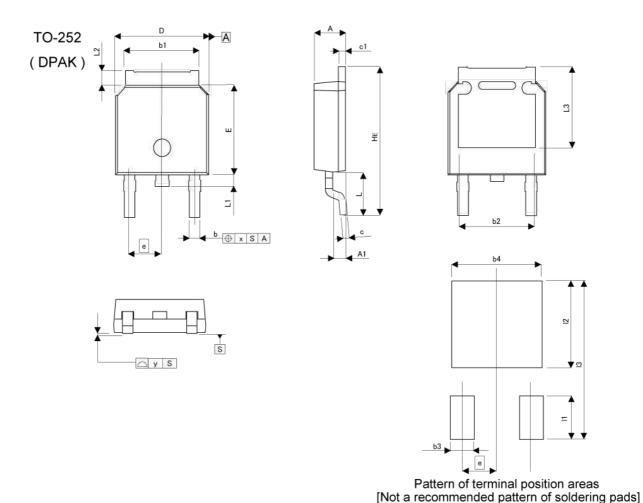


Fig.3-2 Avalanche Waveform



Dimensions



INCHES MILIMETERS DIM MIN MAX MIN MAX 0.083 2.10 0.091 Α 2.30 A1 0.70 1.10 0.028 0.043 b 0.65 0.85 0.026 0.033 0.213 5.10 5.40 b1 0.201 b2 5.10 0.201 0.40 0.60 0.016 0.024 C 0.40 0.60 0.016 0.024 c1 D 6.40 6.80 0.252 0.268 е 0.236 6.00 6.40 0.252 E HE 9.50 10.50 0.374 0.413 0.114 0.70 0.028 L1 0.90 0.035 0.70 0.028 L2 1.30 0.051 L3 0.209 0.10 0.004 X у 0.10 0.004

MILIMETERS **INCHES** DIM MIN MAX MIN MAX b3 1.10 0.043 5.40 0.213 b4 11 2.90 0.114 12 5.50 0.217 13 10.50 0.413

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГАССШ	CLASS II b	CLASSIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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 - [h] Use of the Products in places subject to dew condensation
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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